

DESIGN FOR TESTABILITY (DFT)

- AD-HOC TECHNIQUES
- STRUCTURED TECHNIQUES
- METRICS ARE :
 - CONTROLLABILITY
 - OBSERVABILITY
 - ~~• TESTABILITY~~
 - TESTABILITY

Guidelines

Structured (bit-sliced) design **Avoid random logic**

• minimize redundant hardware **Avoid deep logic**

• use XOR gates (instead of OR)

• Avoid reconverging paths — **THE MAJOR PROBLEM**

• Avoid networks with many levels

• Avoid fanouts
minimize a number of fanouts

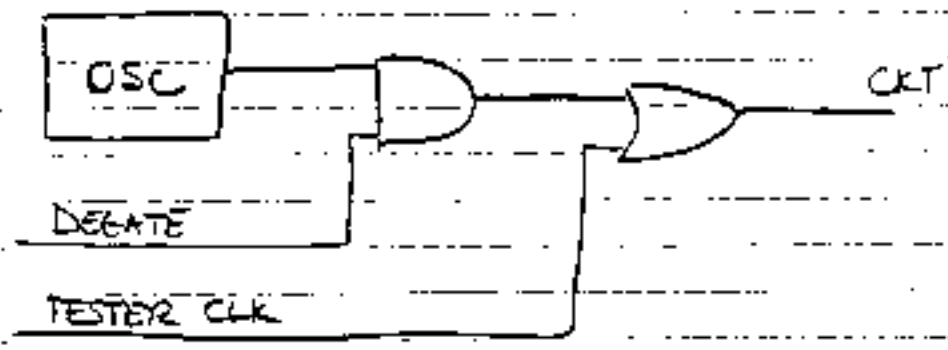
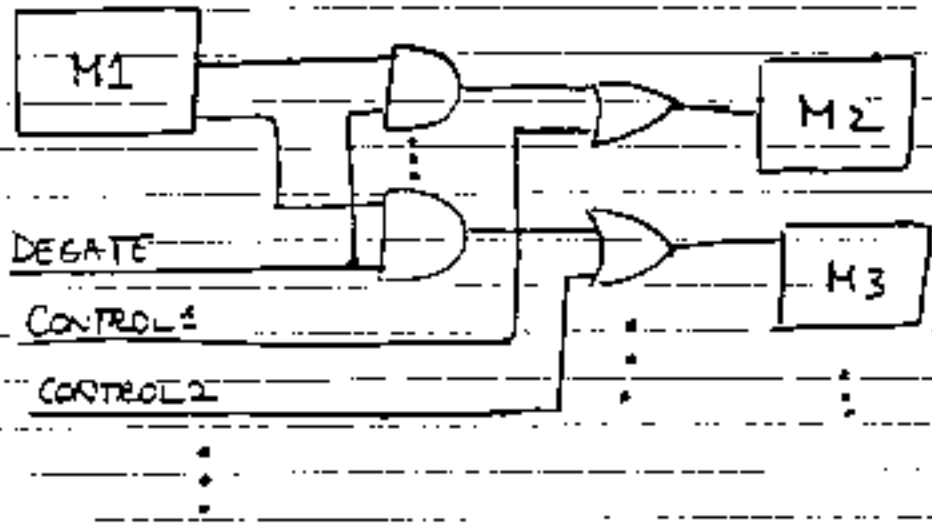
• **Avoid asynchronous logic**

• Use LSSD or SCAN designs

(reduce testing of sequential logic to combinational one)

DFT Ad Hoc TECHNIQUES (OFF-LINE)

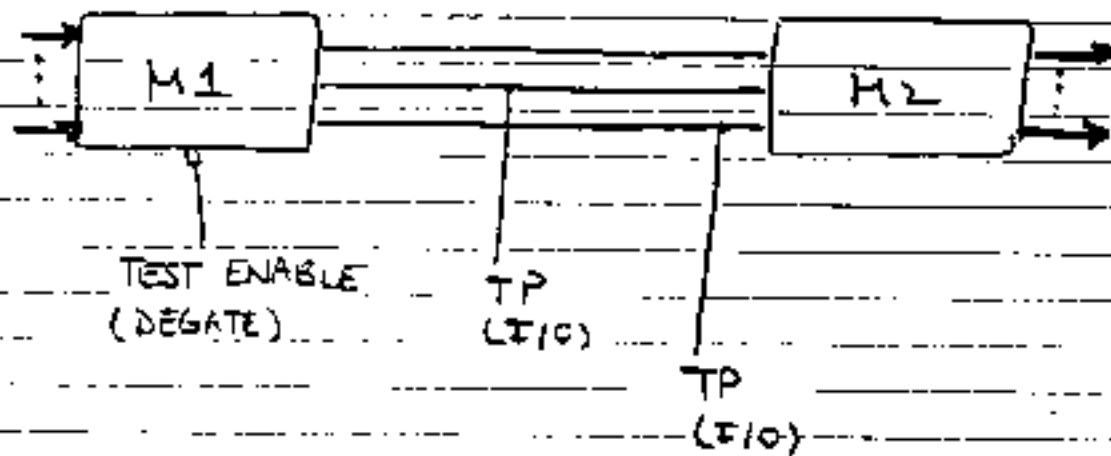
• PARTITIONING & DEGATING



• IMPROVES CONTROLLABILITY

Akers, S.B., "Partitioning for testability," Jnl. Design Automation
Fault Tolerant Computing, vol. 1, Feb. 1977.

• TEST POINT INSERTION

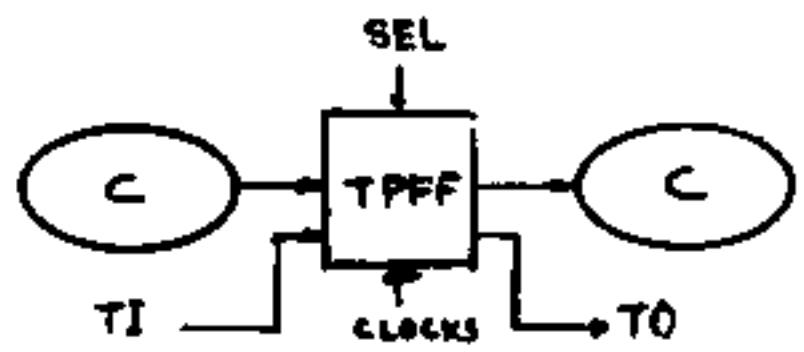
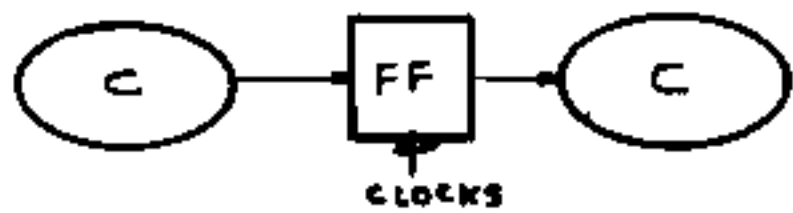
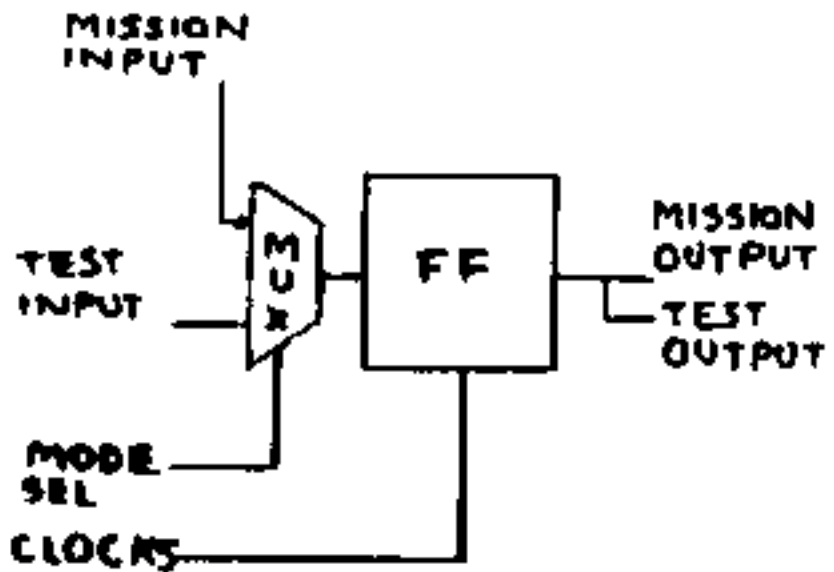


- IMPROVES OBSERVABILITY FOR M1
- IMPROVES CONTROLLABILITY FOR M2

J. D. HAYES, "On Modifying logic networks to improve their diagnosability," IEEE-TC, vol. C-23, pp. 50-62, Jan. 1974.

M. C. Y. WILLIAMS, J. B. ANGELL, "Enhancing testability of LSI circuits via test points and additional logic," IEEE-TC, vol. C-22, pp. 40-50, Jan. 1973.

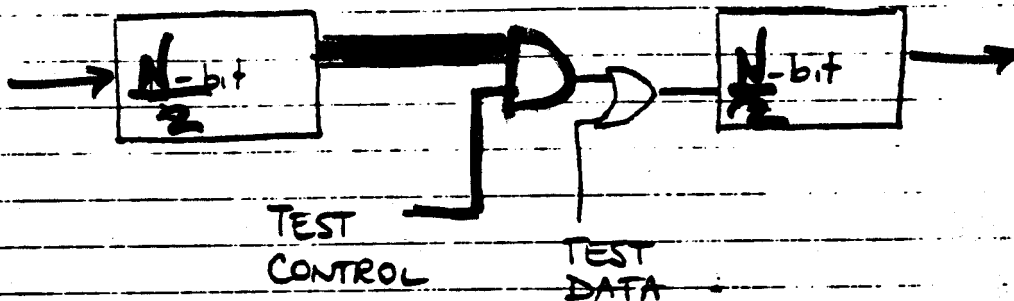
TEST POINT FLIP-FLOPS (TPFFs)



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BREAK LONG COUNTER CHAINS



N-BIT COUNTER REQUIRES MAXIMUM OF 2^N CLOCKS

$\frac{N}{2}$ -BIT " " " $2^{N/2}$

FOR A 16 BIT COUNTER

$$2^N = 64K$$

$$2^{N/2} = 256$$

AVOID ASYNCHRONOUS LOGIC

RACES AND HAZARDS

- DIFFICULT TO DIAGNOSE
- FAULTS MAY INDUCE RACES
- DIFFICULT TO SYNCHRONIZE TESTER
- DIFFICULT TO FAULT SIMULATE

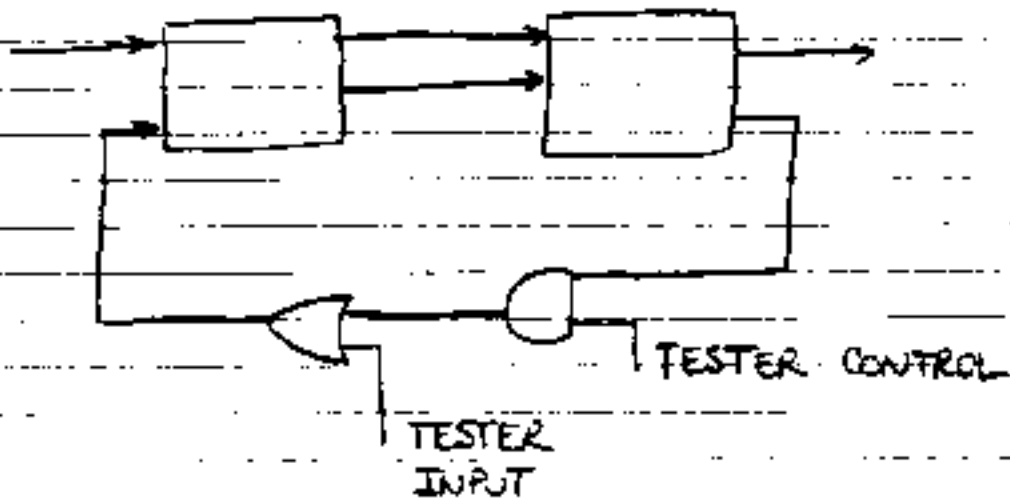
AVOID HIGH FANOUTS & RECONVERGENT PATHS

- DIFFICULT FOR ATG ALGORITHM

AVOID RANDOM LOGIC

- PLA
- ARRAY STRUCTURES
- BIT SLICED DESIGNS

BREAK GLOBAL FEEDBACK LOOPS

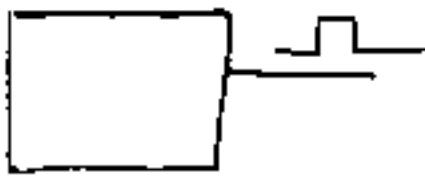


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or delay lines

AVOID MONOSTABLE AND "ONE-SHOT" ELEMENTS
(THE "BANE" OF EVERY TEST ENGINEER!)

- DIFFICULT TO SYNCHRONIZE TO TESTER
- MAY BE DIFFICULT TO RESET/TRIGGER



MONOSTABLE OR ONE SHOT

(10)

AVOID USING "FINE TUNED" OR "CUSTOMIZED"
COMPONENTS

- "TWEAKING" (HUMAN INTERACTION) REQUIRED
"ON-LINE" (EXTRA TEST EQUIPMENT)
- OFTEN REQUIRES ADDITIONAL PARAMETRIC
TESTING

STRUCTURED DFT TECHNIQUES

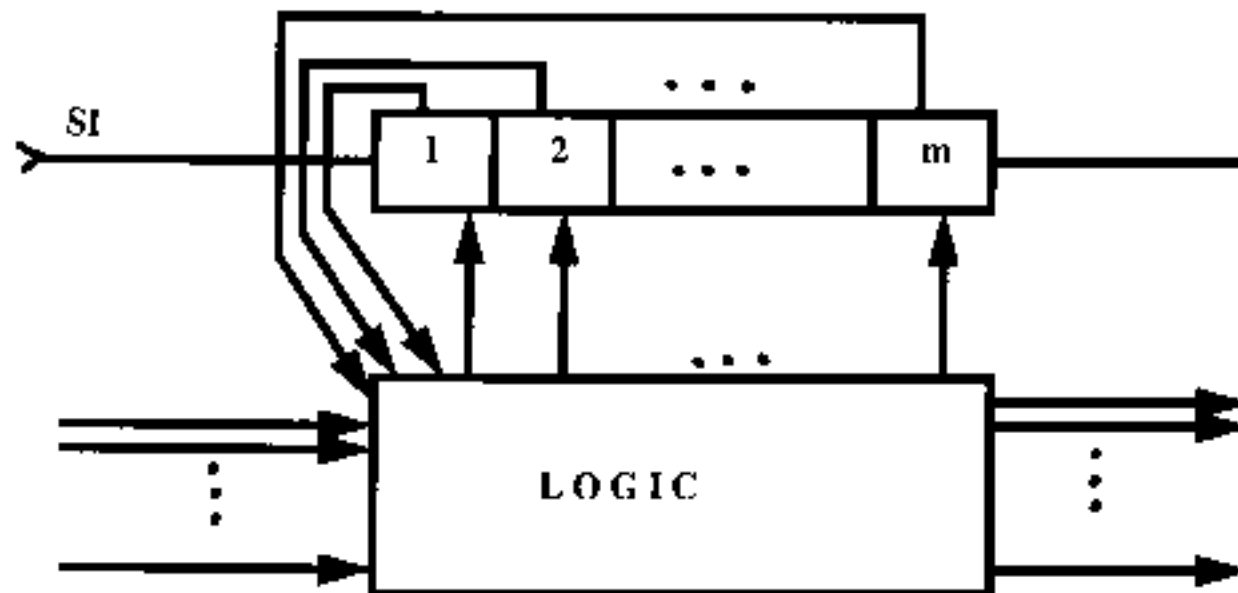
- SCAN DESIGN
 - LSSD
 - SCAN PATH
 - RANDOM ACCESS SCAN
 - SCAN SET
 - GENERIC SCAN

- SIGNATURE ANALYSIS

GOAL:

- REDUCE ATG TO \downarrow CASE
- OVERHEAD
- OFF-LINE & ON-LINE SCAN TESTS

SCAN DESIGN



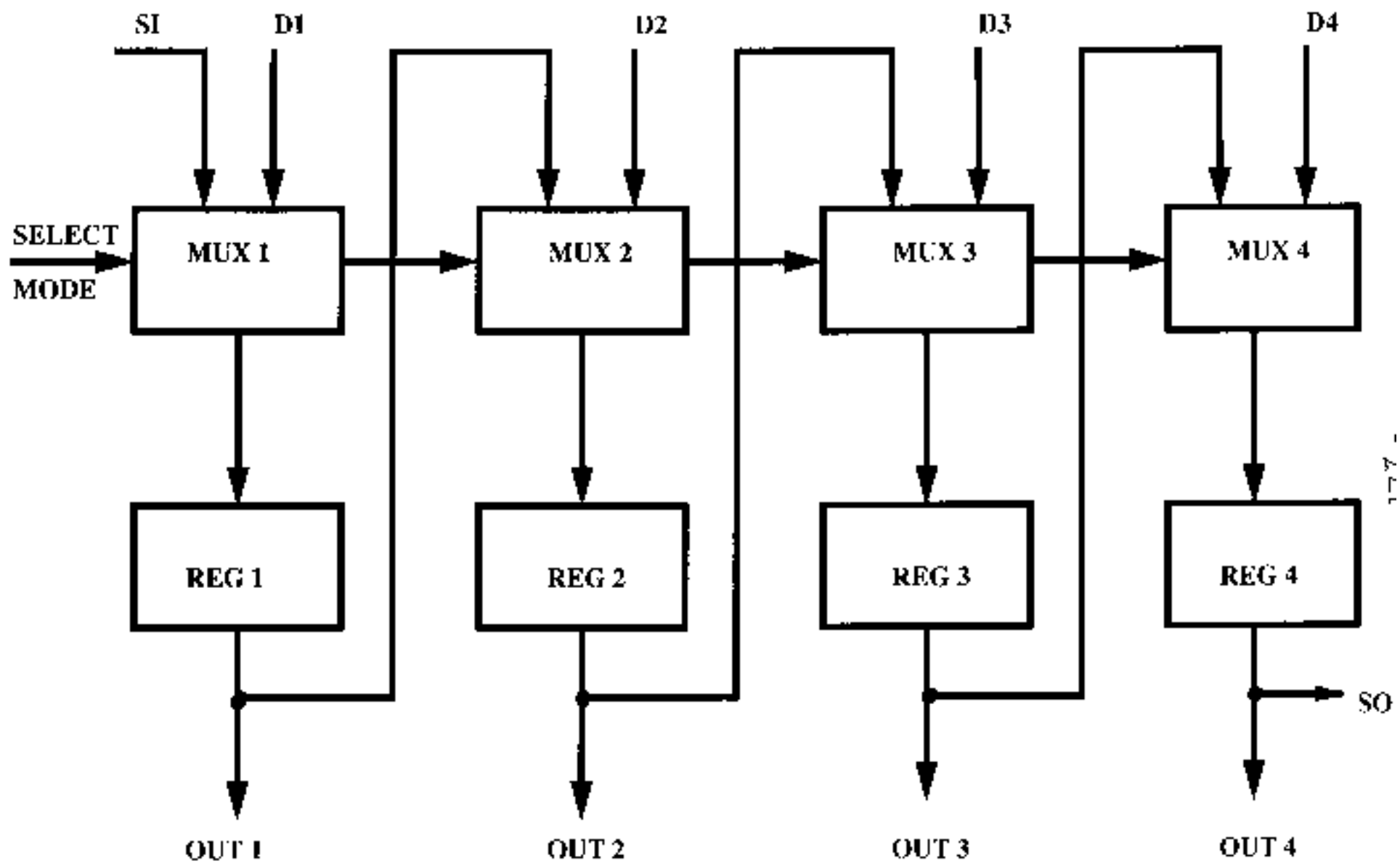
Features :

- Shift register not in data path (may be off chip !);
- " Snapshots " available of system operation;
- Negligible effect on system operation.

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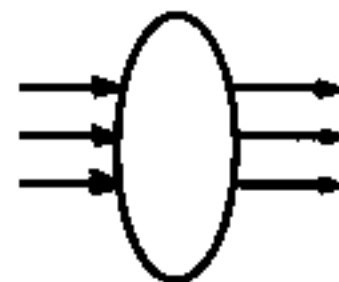
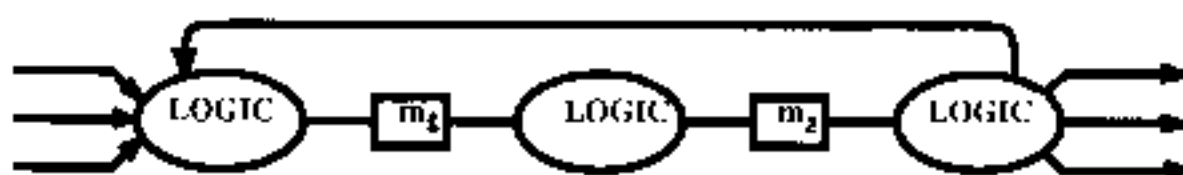
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J.H.Stewart, " Future testing of large LSI circuit cards, ". Dig 1977, Semiconductor Test Sym., Oct. 1977, pp. 6 - 17.

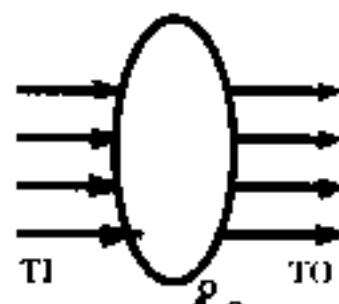
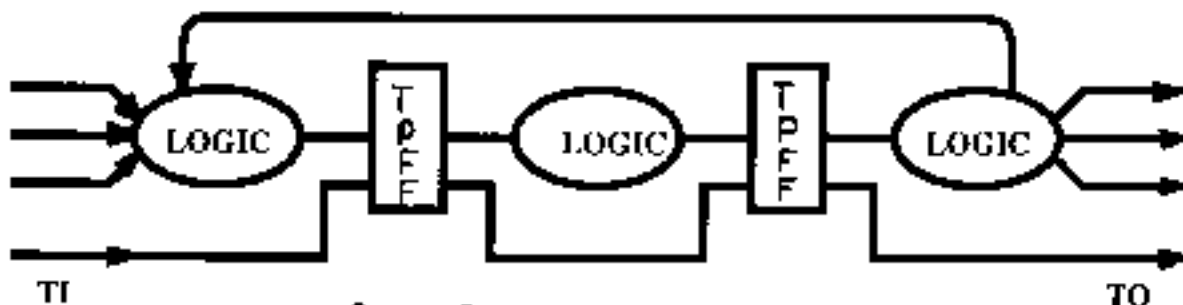


COMPLETE SCAN DESIGN

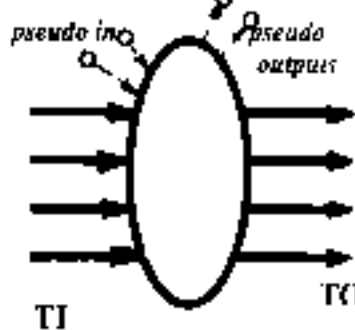
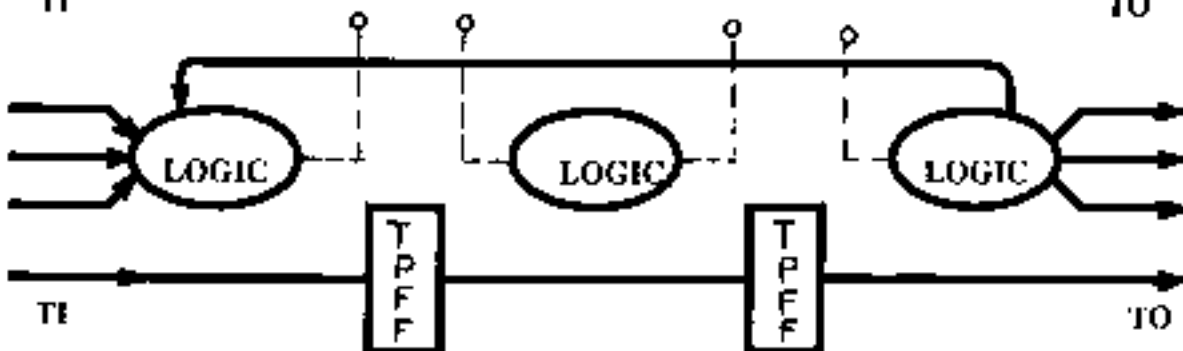
ORIGINAL



WITH COMPLETE SCAN

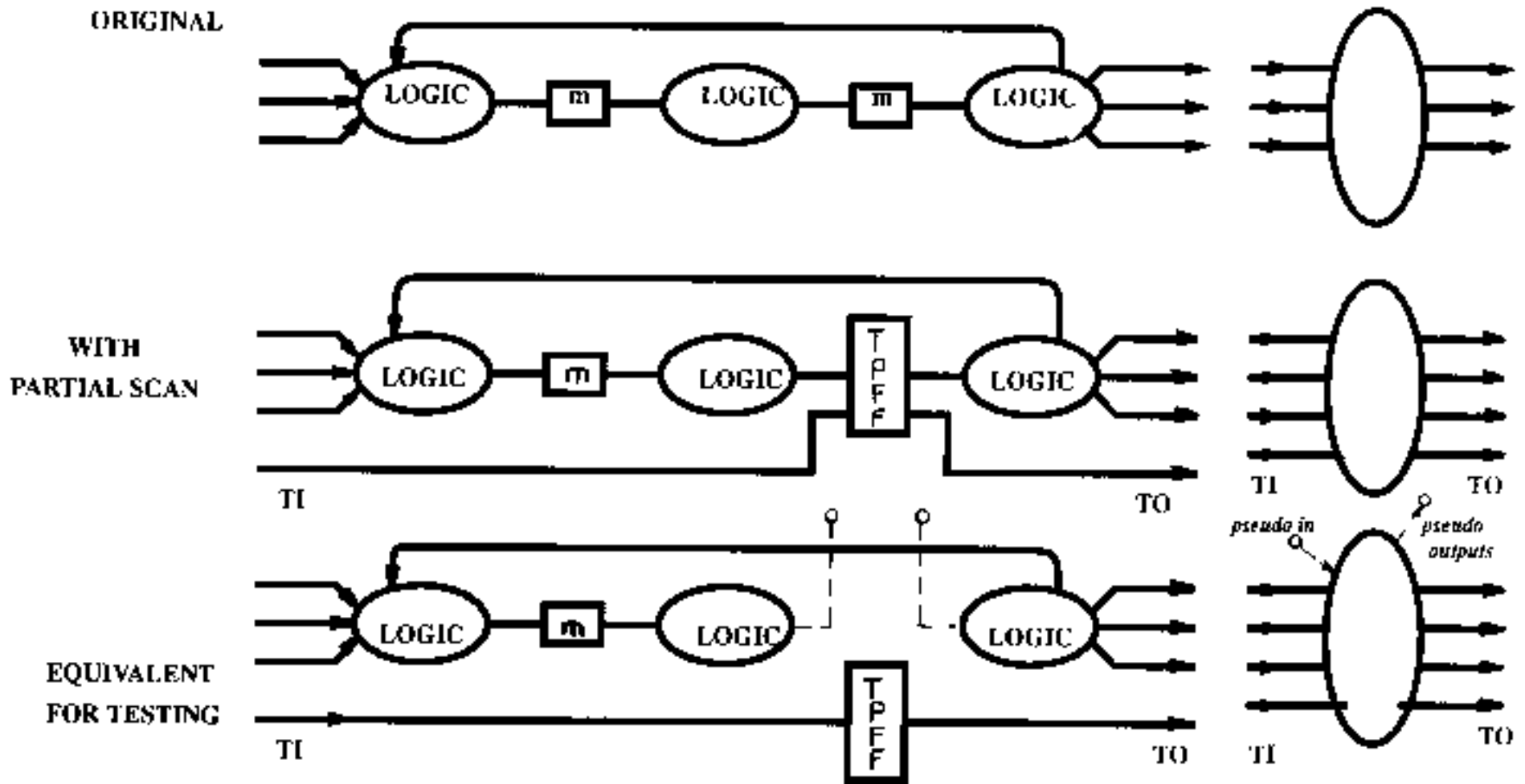


EQUIVALENT FOR TESTING



* Cost proportional to # of internal memory elements.

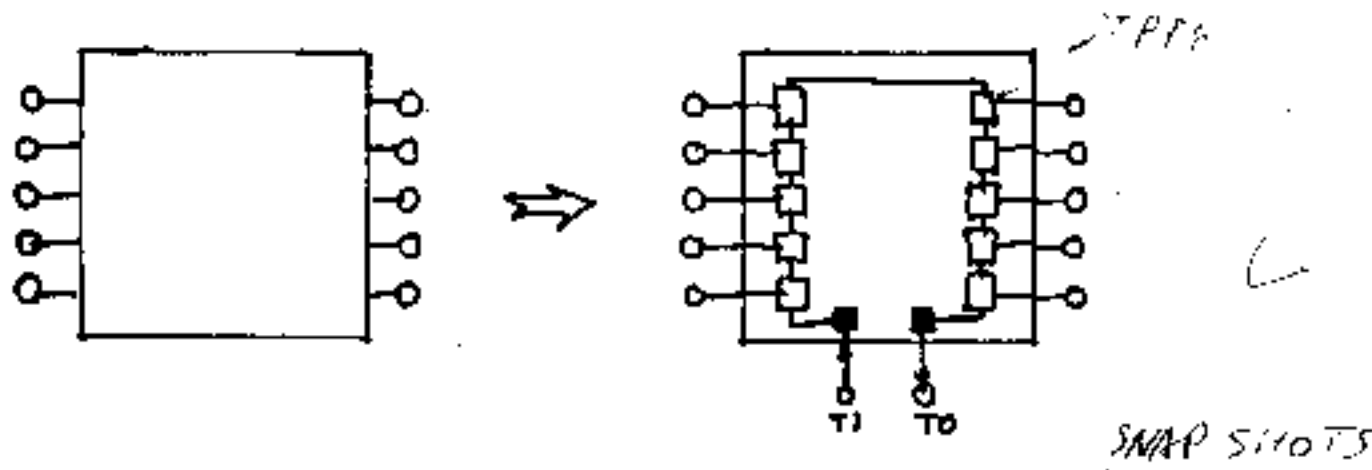
IN - COMPLETE SCAN DESIGN



+ Cost proportional to # of internal loops.

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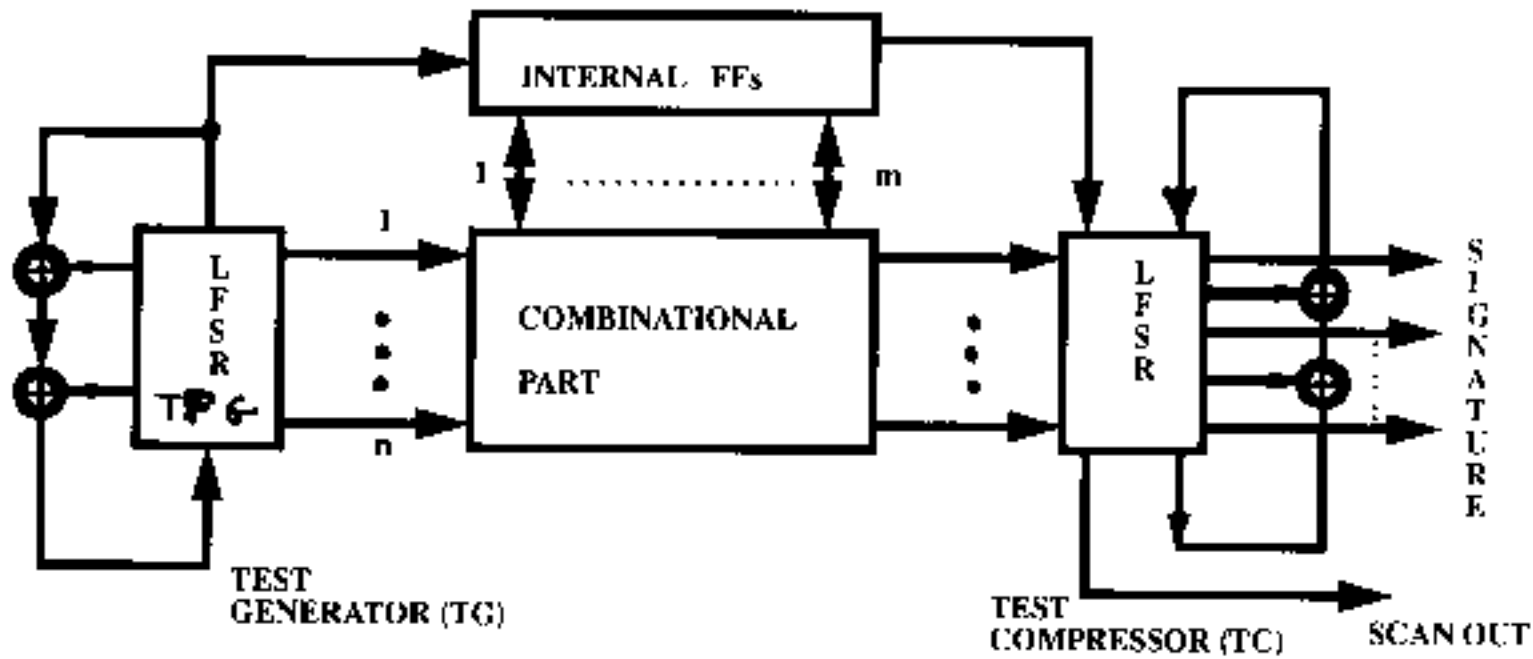
BOUNDARY SCAN (JTAG)



- Cost Proportional to number of I/O pins/pads
- Test Development portable to next assembly level
- Aid to Wafer Probe and In-Situ Testing at all assembly level
- Separability from Analogs etc..
- Works around pin limited tester..

FOR BIST

SCAN REGISTER

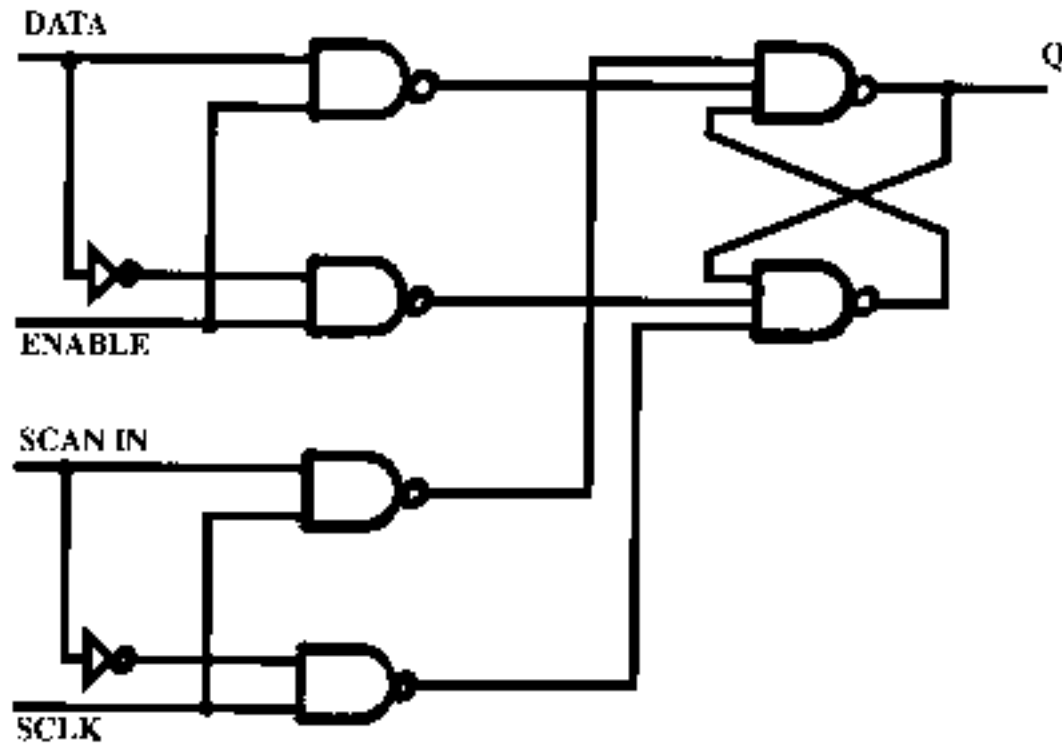


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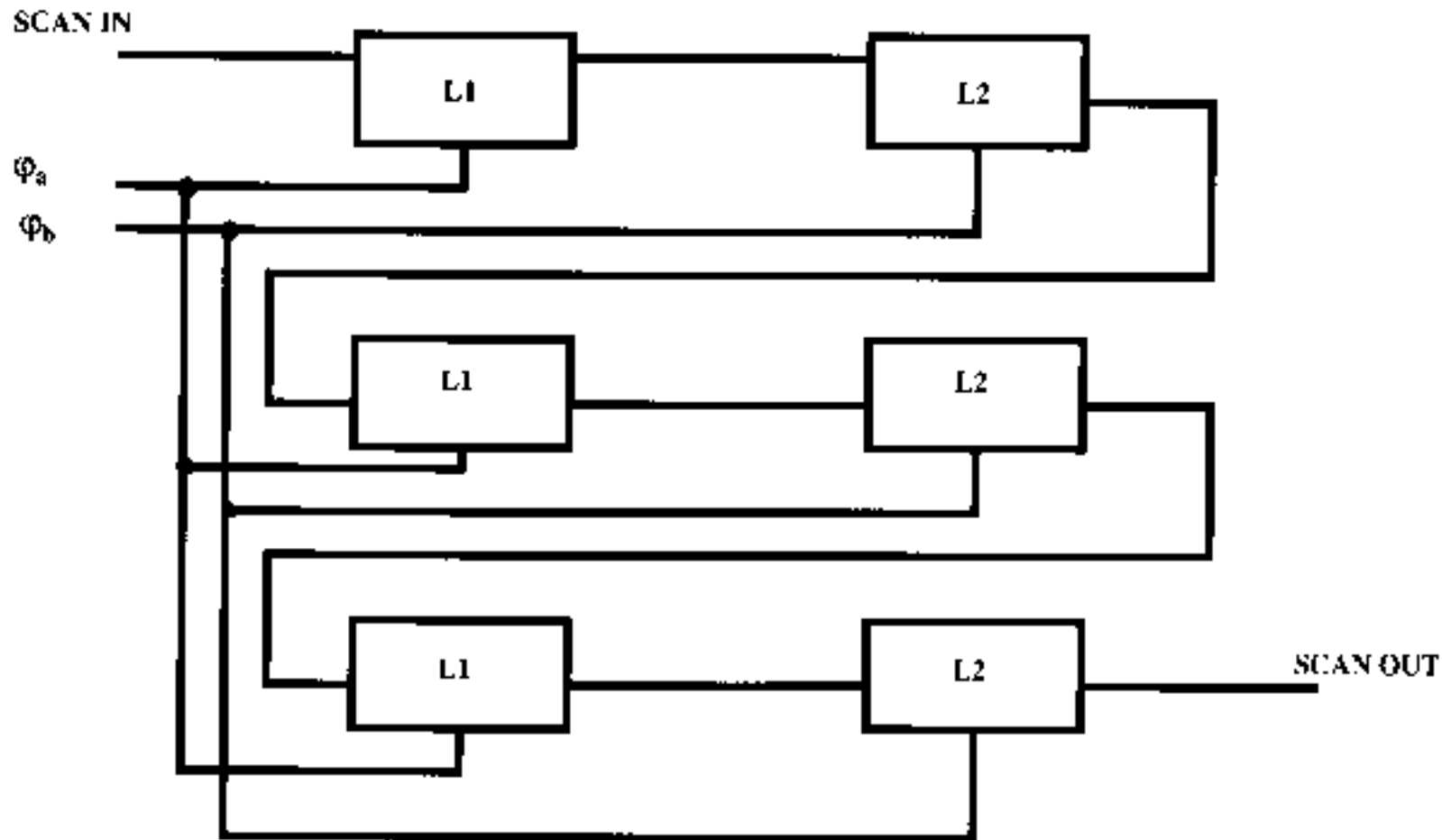
Problem : Maximize pattern coverage number of distinct $(n + m)$ bit inputs to combinational part divided by $2^s - 1$ where s - number of bits in TG ($n \leq s$)

LEVEL SENSITIVE SCAN DESIGN (LSSD).

Level Sensitive SCAN Design (IBM).



LEVEL SENSITIVE SCAN DESIGN (LSSD).



Modifications of SCAN.

Total(complete)SCAN --> 15% overhead;

Partial(incomplete)SCAN;

I/O SCAN (boundary SCAN), JTAG;

RAM SCAN --> 80% overhead.

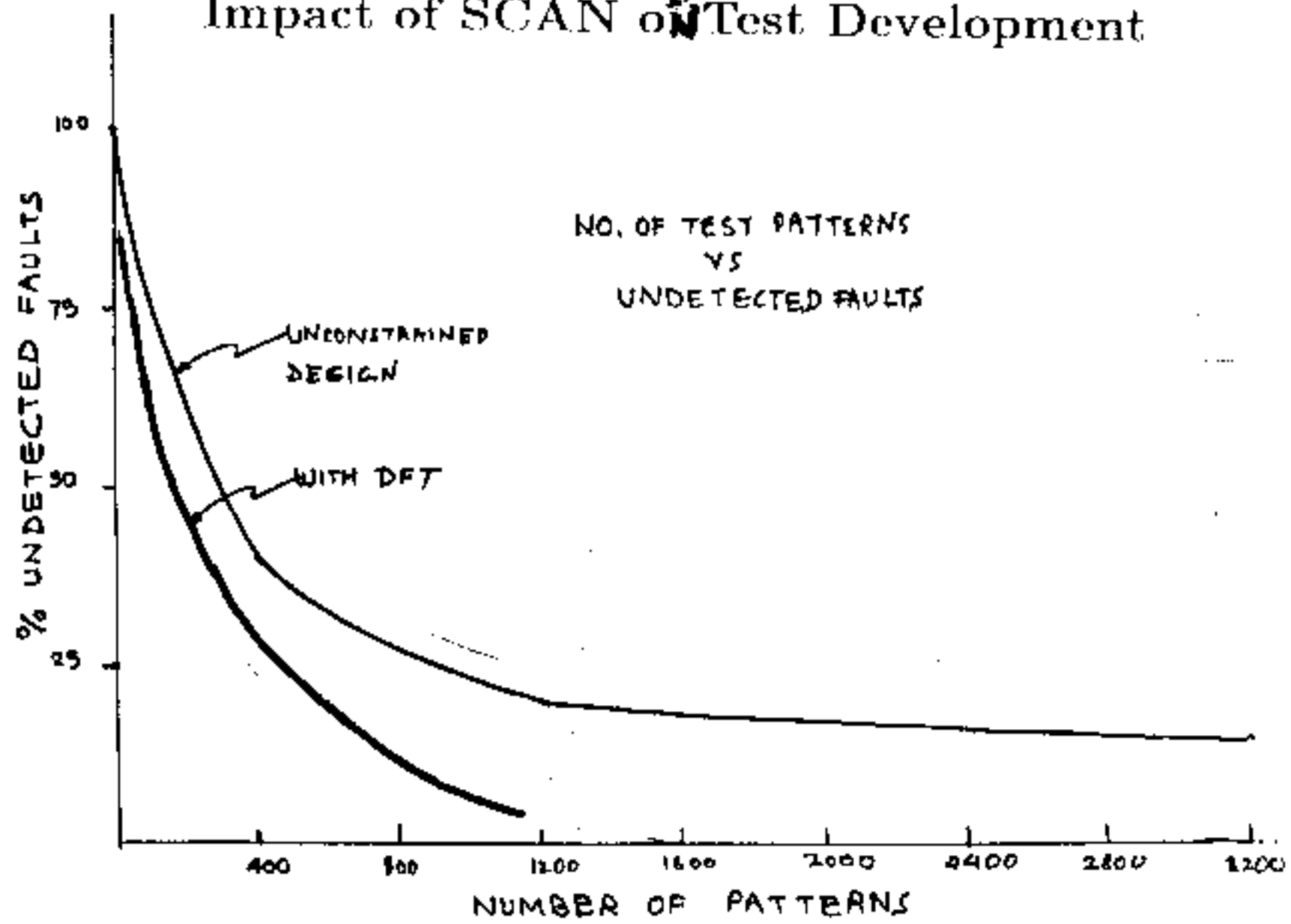
Solution of the pattern coverage problem can be found in :

P. Nagvajara, M. G. Karpovsky, L. B. Levitin

“ Pseudorandom Test Patterns Generation for Boundary SCAN Design “,

Journal of Electronic Testing, March, 1991.

Impact of SCAN on Test Development



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SUMMARY. *on DFT.*

SCAN design offers many advantages in test development and testing during a products life cycle

- TPFs and SCAN paths for internal *Controllability, Observability, etc.*
- Complete SCAN offers maximum benefits but In-complete Scan can also offer significant testing advantages at reasonable costs

BiST offers quick, at-speed testing with minimal test data storage and handling

- POLYDIV (LFSR based) self-test most popular, effective, and economical
- Cost reduced by sharing with system hardware and by externally supporting the self-test control

SUMMARY...

- **POLYDIV BiST and Serial SCAN are Made For Each Other**
- **Techniques applicable at any level of design but costs favor that DFT Implementation begin at the chip level**
- **Testability Support Chips can facilitate DFT implementation at module/system level**
 - *Concatenable Polydivider chips, central self-test control chips, etc can help to reduce IC count and testability design effort*